



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-02-12
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacopello	Representative Title	IPD MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STD7ANM60N	TMDP*M260A62	A	SHENZHEN B/E	2016-02-12
Amount	UoM	Unit type	ST ECOPACK Grade	
310.00	mg	Each	ECOPACK1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	6.5, 6.1, 2.3	3	GULL WING	
Comment	TO 252 DPAK			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	TMDP*M260A62					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	3.931	mg	supplier	die	Silicon (Si)	7440-21-3		3.774	mg	960051	12171
				supplier	metallization	Aluminium (Al)	7429-90-5		0.075	mg	19084	242
				supplier	Passivation	Silicon Nitride	12033-89-5		0.018	mg	4580	58
				supplier	Passivation	Silicon Oxide	7631-86-9		0.027	mg	6870	87
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.002	mg	509	6
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.026	mg	6616	84
Leadframe	Copper & its alloys	166.150	mg	supplier	back side metallization	Silver (Ag)	7440-22-4		0.009	mg	2290	29
				supplier	alloy	Copper (Cu)	7440-50-8		164.152	mg	987975	529523
				supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		0.330	mg	1986	1065
				supplier	alloy	Cobalt (Co)	7440-48-4		0.462	mg	2781	1490
				supplier	metallization	Nickel (Ni)	7440-02-0		1.199	mg	7216	3868
				supplier	metallization	Phosphorus (P)	12185-10-3		0.007	mg	42	23
Soft solder	Solder	3.751	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high met	3.582	mg	954945	11555
				supplier	solder	Silver (Ag)	7440-22-4		0.094	mg	25060	303
				supplier	solder	Tin (Sn)	7440-31-5		0.075	mg	19995	242
				supplier	wire	Aluminium (Al)	7429-90-5		0.266	mg	998124	858
Bonding wires	Other inorganic materials	0.267	mg	supplier	wire	Magnesium (Mg)	7439-95-4		0.001	mg	1876	2
				supplier	wire	Silica, vitreous	60676-86-0		108.695	mg	806008	350629
Encapsulation	Other Organic Materials	134.856	mg	supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		9.440	mg	70001	30452
				supplier	mold compound	Phenol resin	9003-35-4		5.394	mg	39998	17400
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		8.091	mg	59997	26100
				supplier	mold compound	Antimony Trioxide	1309-64-4		1.618	mg	11998	5219
				supplier	mold compound	Brominated Epoxy Resin	40039-93-8		0.944	mg	7000	3045
				supplier	mold compound	Carbon black	1333-86-4		0.674	mg	4998	2174
Connections coating	Solder	1.045	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	3371